



Japan TC Chapter of Traceability Global Technical Committee Meeting Summary and Minutes

Japan Standards Winter Meetings 2014 in conjunction with SEMICON Japan 2014 Friday, December 5, 2014, 9:00 a.m. – 11:00 a.m. Tokyo Big Sight Conference Tower, Tokyo, Japan

Next Committee Meeting

Monday, April 27, 2015, 3:00 p.m. – 5:00 p.m.

Committee Announcements (optional)

None

Table 1 Meeting Attendees

Italics indicates virtual participants

Co-Chairs: Yoichi Iga (JSA), Hirokazu Tsunobuchi (Keyence)

SEMI Staff: Chie Yanagisawa **Attendee:** 10 + **SEMI:** 1

Company	Last	First	Company	Last	First
Hitachi Kokusai Electric	Matsuda	Mitsuhiro	OMRON	Otsuka	Hiroshi
HST-Vision	Sasaki	Kunihiko	SUMCO	Nakai	Tetsuya
Intel	Goldstein	Mike	Self	Yoshise	Masanori
JSA (Japan Standards Association)	Iga	Yoichi	Tokyo Electron	Mashiro	Supika
Keyence	Tsunobuchi	Hirokazu			
Kumai Consulting	Kumai	Sadao	SEMI Japan	Yanagisawa	Chie

^{*} alphabetical order by company name

Table 2 Leadership Changes

None

Table 3 Ballot Results (or move to Section 4, Ballot Review)

Passed ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

Failed ballots and line items were returned to the originating task forces for re-work and re-balloting.

Document #	Document Title	Committee Action
	Revision of SEMI T7-0303 (Reapproved 0709), Specification for Back Surface Marking of Double-Side Polished Wafers with a Two-Dimensional Matrix Code Symbol	Passed with editorial changes

Table 4 Authorized Ballots (or move to Section 7, New Business)

None

Table 5 Authorized Activities (or move to Section 7, New Business)

None

Table 6 New Action Items (or move to Section 8, Action Item Review)

Item #	Assigned to	Details
	Interoperability	To revise the SNARF for Line Item Revision to Doc. 5752: Revision of SEMI T7-0303 (Reapproved 0709), Specification for Back Surface Marking of Double-Side Polished Wafers with a Two-Dimensional Matrix Code Symbol





Table 7 Previous Meeting Actions Items (or move to Section 8, Action item Review)

Item #	Assigned to	Details
20140929#1	SEMI Staff	To get the final ballot #5752 draft with Background Statement to be sent, ASAP
20140929#2	Hirokazu Tsunobuchi (Keyence)	To convey the conclusion by Japan Fiducial Mark Interoperability Task Force for the ballot result of #5752 to TF leader of NA Five Year Review Task Force, ASAP => CLOSE
20140929#3	Hirokazu Tsunobuchi (Keyence)	To convey the idea to wish to prepare #5752 ballot review at Fiducial Mark Interoperability Task Force, not at NA Five Year Review Task Force and propose to set up teleconference with Fiducial Mark Interoperability Task Force and NA Five Year Review Task Force jointly on Monday evening (19:30-), November 24 / Tuesday morning (9:30-), November 25 [Japan Standards Time], ASAP => CLOSE
20140929#4	SEMI Staff	To convey the related members of NA side that #5752 ballot adjudication will be held at Japan Traceability TC Chapter meeting in the morning of December 5, ASAP. => CLOSE

1 Welcome, Reminders, and Introductions

Hirokazu Tsunobuchi (Keyence) called the meeting to order at 9 a.m. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

2 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting.

Motion:	To approve the minutes of the previous meeting as written.		
By / 2 nd :	Tetsuya Nakai (SUMCO) / Sadao Kumai (Kumai Consulting)		
Discussion:	None		
Vote:	6 in favor and 0 oppose. Motion passed.		

3 Liaison Reports

3.1 North America

No report.

3.2 SEMI Staff Report

Chie Yanagisawa (SEMI Japan) gave the SEMI Staff Report. Of note:

- Global SEMI Events
- Global Standards Meetings Schedule
- SEMICON Japan Meeting Schedule
- Ballot Critical Dates
- New Regulations and Procedure Guide
- Publication Update
- Contact Information

Attachment: 01_SEMI Staff Report 2014 December_R0.3





4 Ballot Review

4.1 Ballot #5752 : Revision of SEMI T7-0303 (Reapproved 0709), Specification for Back Surface Marking of Double-Side Polished Wafers with a Two-Dimensional Matrix Code Symbol

Doc. #5752 was developed by the North America TF Chapter of Traceability Global Technical Committee. As mentioned in the previous meeting minutes, Japan TC Chapter of Traceability Global Technical Committee reached the conclusion that it accepted the proposal by the North America Traceability TC Chapter that Ballot #5752 would be adjudicated at the next Japan Traceability TC Chapter in December 2014. After that the proposal was also approved by Traceability GCS on October 14, 2014. The ballot was reviewed and adjudicated at the Japan TC Chapter meeting of Traceability Global Technical Committee held on December 5, 2014 in conjunction with SEMICON Japan 2014.

The committee action for the document is listed in the Table 3 "Ballot Results". The details of ballot review are found in the attachment.

Attachment: 02_Ballot_Review_for_5752

5 Subcommittee & Task Force Reports

5.1 Five Year Review Task Force

Hirokazu Tsunobuchi (Keyence) reported there was no update for the task force.

5.2 Japan PV Traceability Task Force

Hirokazu Tsunobuchi (Keyence) reported there was no update for the task force.

5.3 Fiducial Mark Interoperability Task Force

Hirokazu Tsunobuchi (Keyence) reported for Fiducial Mark Interoperability Task Force. Of note:

- TF reviewed the negatives and the comments to Ballot #5752
 - o TF proposed John Valley (SunEdison) that he would withdraw his reject vote to #5752 and TF would adopt his negative as a new business for the next revision to SEMI T7-mmyy (Doc. #5752) instead. He agreed to that proposal and the reject was withdrawn.
- TF has decided to propose "pass the ballot with editorial change"
- A new SNARF for Line Item Revision to SEMI T7-mmyy (Doc. #5752) to be proposed at the "New Business" section at this meeting.

Attachment: 03_20141205FMI-TFr0

6 Old Business

None





7 New Business

7.1 Proposal of new SNARF for Line Item Revision to SEMI T7-mmyy (Doc. #5752), "Specification for Back Surface Marking of Double-Side Polished Wafers with a Two-Dimensional Matrix Code Symbol"

Although the proposal of new SNARF for Line Item Revision to SEMI T7-mmyy (Doc. 5752) was made, the Japan TC Chapter discussed and the proposal was made as following.

Motion:	Rewrite the SNARF and reflect other issues		
By / 2 nd :	Tetsuya Nakai (SUMCO) / Mitsuhiro Matsuda (Hitachi Kokusai Electric)		
Discussion:	Due to insufficient specification for special relationship between SEMI T7 code and 300mm non silicon or non SEMI M1 wafers or larger, either the scope or Table 1 need to be changed. There is also a discussion that SEMI T7 should not include the special relationship in the first place. The Fiducial Mark Interoperability TF needs more time to decide how to resolve this issue of the current SEMI T7 and concluded the SNARF approval should be postponed.		
Vote:	7 in favor and 0 opposed. Motion passed .		

Action Item 1: Fiducial Mark Interoperability TF to revise the SNARF for Line Item Revision to Doc. 5752: Revision of SEMI T7-0303 (Reapproved 0709), "Specification for Back Surface Marking of Double-Side Polished Wafers with a Two-Dimensional Matrix Code Symbol".

8 Action Item Review

8.1 Open Action Items

None

8.2 New Action Items

Chie Yanagisawa (SEMI Japan) reviewed the new action item. This can be found in the New Action Items table at the beginning of these minutes.

9 Next Meeting and Adjournment

The next meeting of the Japan TC Chapter of Traceability Global Technical Committee is to be decided.

The next meeting was scheduled on Monday, April 27, 2015 at a later date.





Respectfully submitted by:

Chie Yanagisawa Senior Standard Coordinator SEMI Japan

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Minutes approved by:

Yoichi Iga (JSA), Co-chair	December 18, 2015
Hirokazu Tsunobuchi (Keyence), Co-chair	December 18, 2015

Table 8 Index of Available Attachments #1

#	Title	#	Title
01	SEMI Staff Report 2014 December_R0.3	03	20141205FMI-TFr0
02	Ballot_Review_for_5752		

^{#1} Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.